

SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown voltage, low turn-on voltage and ultrafast switching.

Primarily intended for high level UHF/VHF detection and pulse application with broad dynamic range.



MINIMELF
(Glass)

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	20	V
I_F	Forward Continuous Current	35	mA
P_{tot}	Power Dissipation	430	mW
T_{sig} T_j	Storage and Junction Temperature Range	- 65 to 200	°C
T_L	Maximum Temperature for Soldering during 15s	260	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th} (j-l)$	Junction-leads	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
$V_{(BR)}$	$T_{amb} = 25^\circ C$	$I_R = 10\mu A$	20			V
V_F *	$T_{amb} = 25^\circ C$	$I_F = 1mA$			0.41	V
	$T_{amb} = 25^\circ C$	$I_F = 35mA$			1	
I_R *	$T_{amb} = 25^\circ C$	$V_R = 15V$			0.1	µA

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ C$	$V_R = 0V$	$f = 1MHz$			1.2	pF
τ	$T_{amb} = 25^\circ C$	$I_F = 5mA$	Krakauer Method			100	ps

* Pulse test : $t_p \leq 300\mu s$, $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

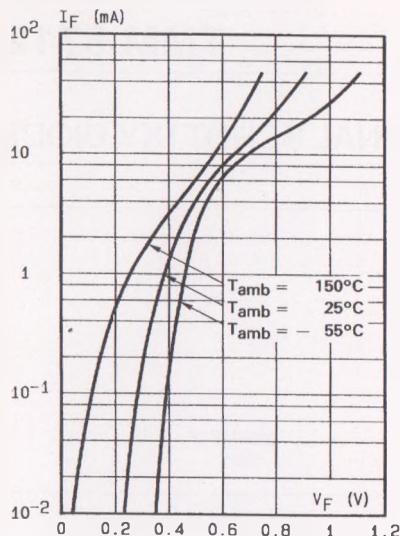


Fig.1 - Forward current versus forward voltage at different temperatures (typical values).

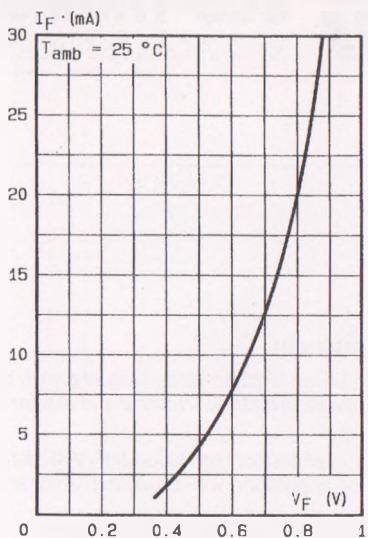


Fig.2 - Forward current versus forward voltage (typical values).

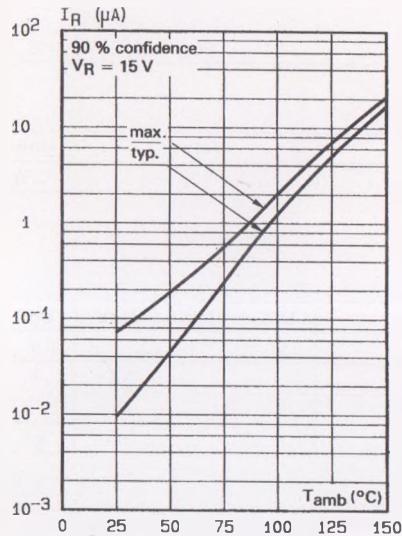


Fig.3 - Reverse current versus ambient temperature.

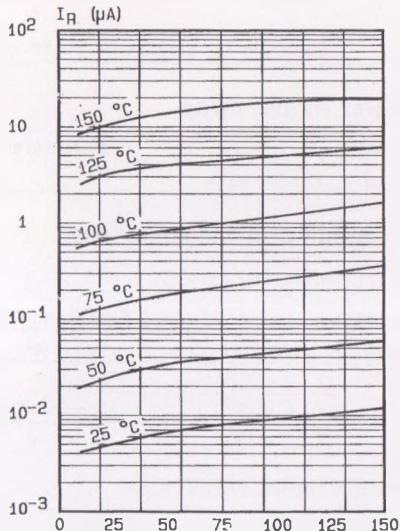


Fig.4 - Reverse current versus continuous reverse voltage (typical values).

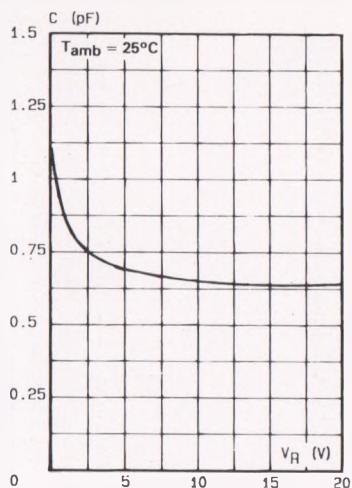


Fig.5 - Capacitance C versus
reverse applied voltage V_R
(typical values).